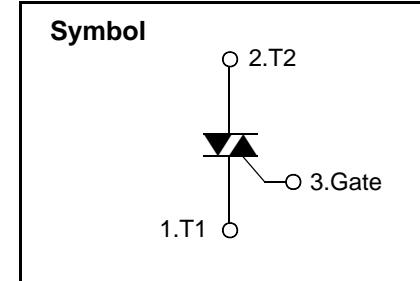
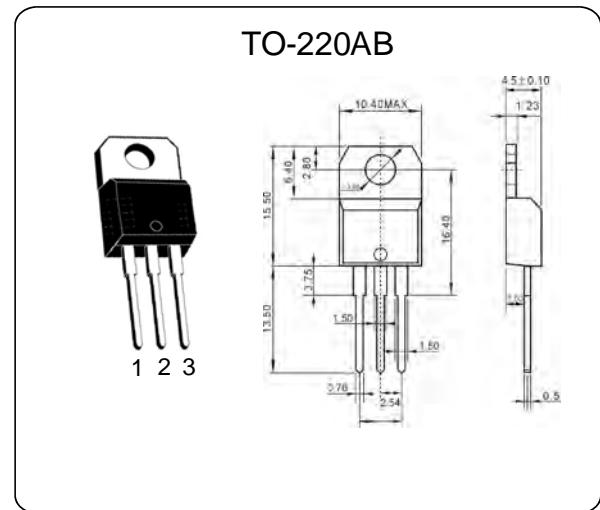


Bi-Directional Triode Thyristor

Designed for high performance full-wave ac control applications where high noise immunity and high commutating di/dt are required.

Features

- Blocking Voltage to 800 V
- On-State Current Rating of 6A RMS at 100°C
- Uniform Gate Trigger Currents in Three Quadrants
- High Immunity to dV/dt-1500V/us minimum at 125°C
- Minimizes Snubber Networks for Protection
- Industry Standard TO-220AB Package
- High Commutating dI/dt- 4.0A/ms minimum at 125°C
- Internally Isolated (2500VRMS)
- These are Pb-Free Devices



Absolute Maximum Ratings

Symbol	Parameter			Value	Unit
$I_{T(RMS)}$	RMS on-state current(full sine wave)	TO-220AB	TC=110 °C	6	A
		TO-220AB Ins.	TC=100 °C		
I_{TSM}	Non repetitive surge peak on-state current(full cycle, T_j initial=25 °C)	F=50Hz	t=20ms	60	A
		F=60Hz	t=16.7ms	65	
I^2t	I^2t Value for fusing	$t_p=10\text{ms}$		31	A^2s
DI/DT	Critical rate of rise of on-state current $IG=2X_{IGT, tr \leq 100\text{ns}}$	F=120Hz	$T_j=125\text{ °C}$	50	$\text{A}/\mu\text{s}$
I_{GM}	Peak gate current	$t_p=20\text{\mu s}$	$T_j=125\text{ °C}$	2	A
$P_{G(AV)}$	Average gate power dissipation	$T_j=125\text{ °C}$		0.5	W
T_{stg}	Storage junction temperature range			-40 to +150	°C
T_j	Operating junction temperature range			-40 to +125	



BTA06-800B

Electrical Characteristics (T_j=25°C, unless otherwise specified)

Snubberless™ and Logic Level(3 quadrants)

Symbol	Test conditions	Quadrant	BTA06-800B		Unit
I _{GT} (1)	V _D =12V R _L =30Ω	I - II -III -IV	MAX	50	mA
V _{GT}		I - II -III -IV	MAX	1.3	V
V _{GD}	V _D =V _{DRM} R _L =3.3KΩ T _j =125°C	I - II -III -IV	MIN	0.2	V
I _H (2)	I _T =100mA		MAX	50	mA
I _L	I _G =1.2I _{GT}	I - II -III -IV	MAX	70	mA
		II		80	
D _v / D _t (2)	V _D =67%V _{DRM} Gate open T _j =125°C		MIN	1000	V/us
(Dl/dt)c(2)	(Dv/dt) _c =0.1 V/us T _j =125°C		MIN	-	A/ms
	(Dv/dt) _c =10V/us T _j =125°C			-	
	Without snubber T _j =125°C			7	

Standard (4Quadrants)

Symbol	Test conditions	Quadrant	BTA06-800B		Unit
I _{GT} (1)	V _D =12V R _L =30Ω	I - II -III IV	MAX	50 100	mA
V _{GT}		ALL		1.3	V
V _{GD}	V _D =V _{DRM} R _L =3.3KΩ T _j =125°C	ALL	MIN	0.2	V
I _H (2)	I _T =500mA		MAX	50	mA
I _L	I _G =1.2I _{GT}	I - III- IV	MAX	50	mA
		II		100	
(Dl/dt)(2)	V _D =67%V _{DRM} Gate open T _j =125°C		MIN	400	V/us
(Dl/dt)c(2)	(Dv/dt) _c =3.5 A/ms T _j =125°C		MIN	10	V/us

Static Characteristics

Symbol	Test conditions			Value	Unit
V _{TM} (2)	I _{TM} =5A t _p =380us	T _j =25°C	MAX	1.70	V
V _{to} (2)	Threshold voltage	T _j =125°C	MAX	0.85	V
R _d (2)	Dynamic resistance	T _j =125°C	MAX	50	mΩ
I _{DRM} I _{RRM}	V _{DRM} =V _{RRM}	T _j =25°C	MAX	5	uA
		T _j =125°C		1	mA
V _{DRM} /V _{RRM}	Voltage	T _j =25°C	MIN	800	V

Note 1: minimum IGT is guaranteed at 5% of IGT max

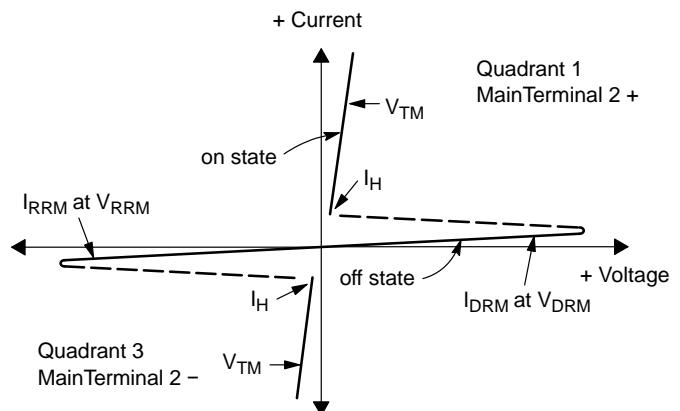
Note 2: for both polarities of A2 referenced to A1

Thermal Resistances

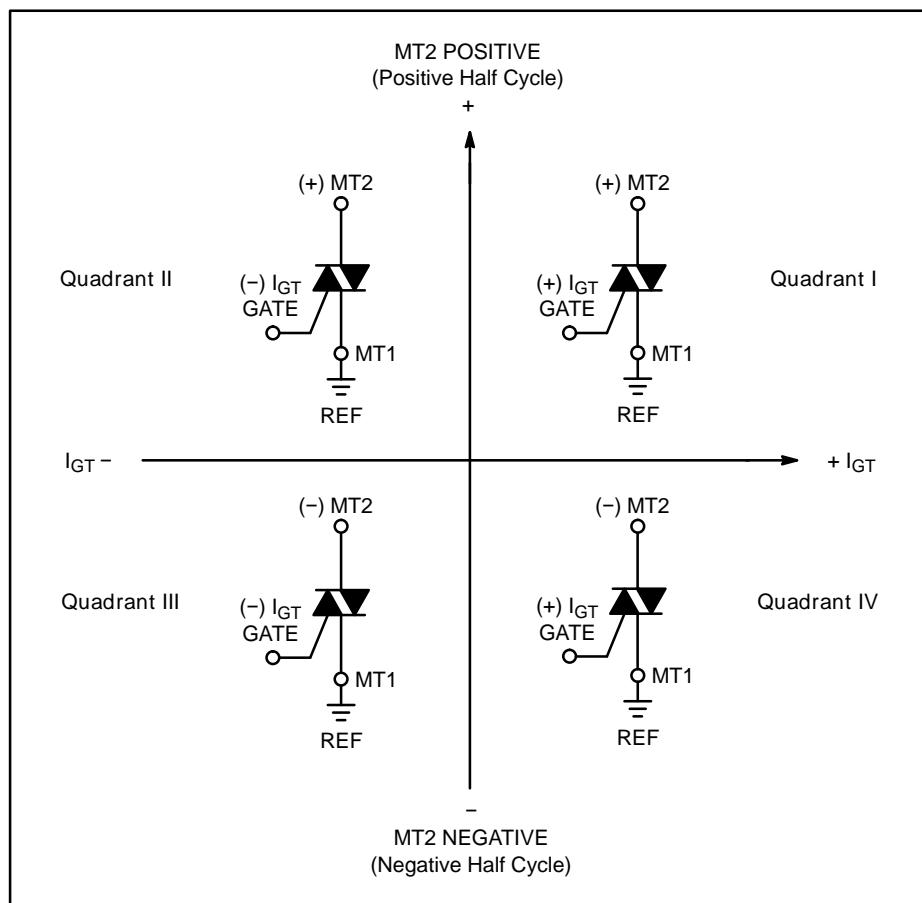
Symbol	Parameter	Value	Unit
R _{th} (J-C)	Junction to case(AC)	3.0	°C/W

Voltage Current Characteristic of Triacs (Bidirectional Device)

Symbol	Parameter
V_{DRM}	Peak Repetitive Forward Off State Voltage
I_{DRM}	Peak Forward Blocking Current
V_{RRM}	Peak Repetitive Reverse Off State Voltage
I_{RRM}	Peak Reverse Blocking Current
V_{TM}	Maximum On State Voltage
I_H	Holding Current



Quadrant Definitions for a Triac



All polarities are referenced to MT1.

With in-phase signals (using standard AC lines) quadrants I and III are used.

Description

Fig. 1: Maximum power dissipation versus RMS on-state current (full cycle).

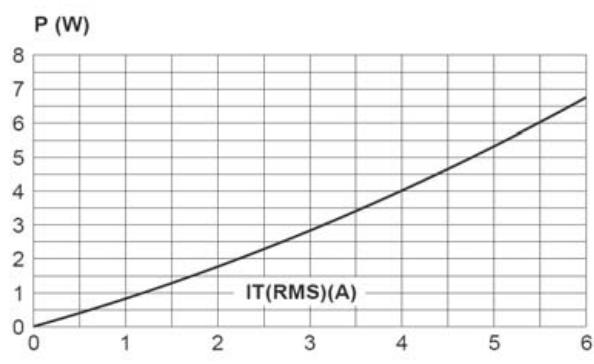


Fig. 2: RMS on-state current versus case temperature (full cycle).

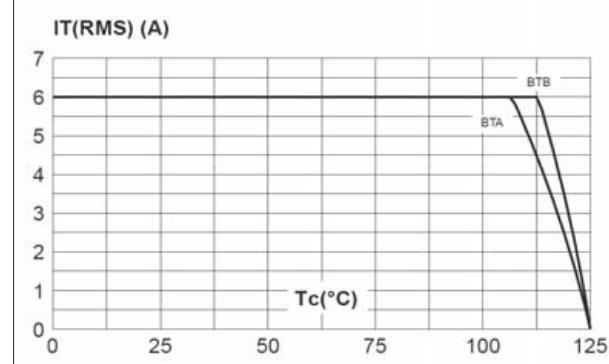


Fig. 3: Relative variation of thermal impedance versus pulse duration.

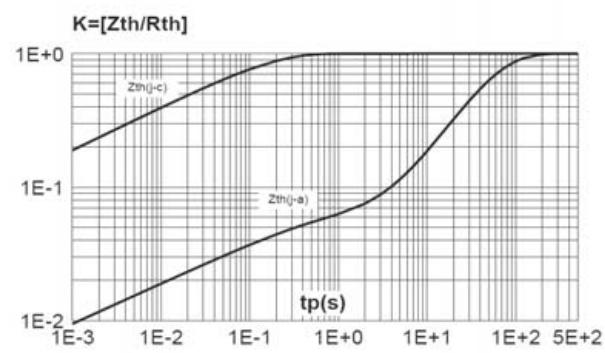


Fig. 4: On-state characteristics (maximum values).

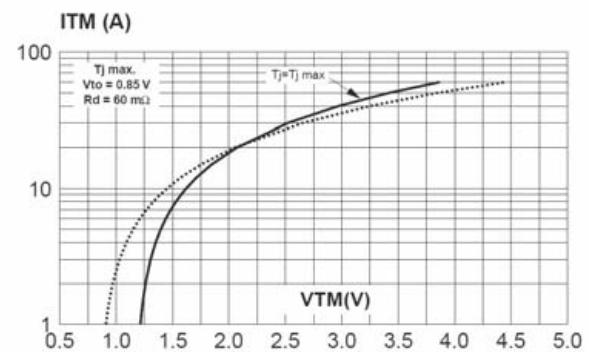


Fig. 5: Surge peak on-state current versus number of cycles.

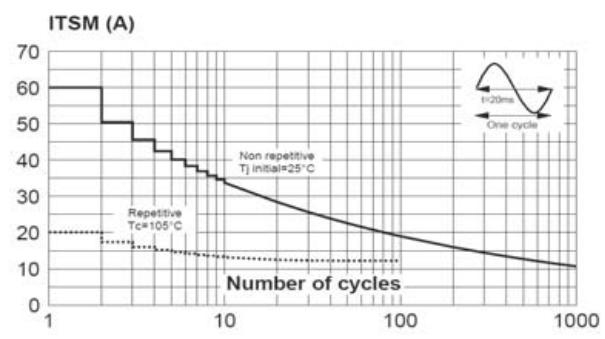
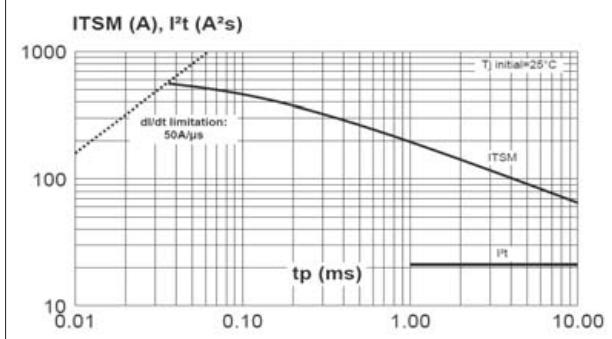


Fig. 6: Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp < 10ms, and corresponding value of I²t.



Description

Fig. 7: Relative variation of gate trigger current, holding current and latching current versus junction temperature (typical values).

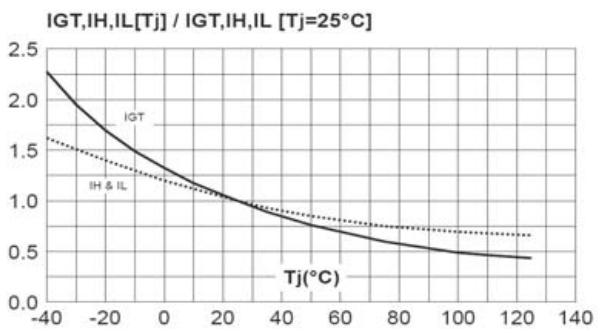


Fig. 8-1: Relative variation of critical rate of decrease of main current versus (dV/dt)c (typical values). Snubberless & Logic Level Types

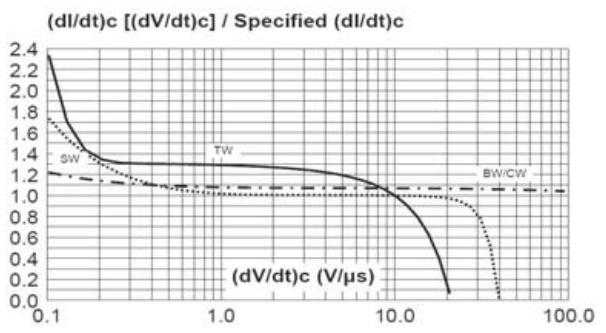


Fig. 8-2: Relative variation of critical rate of decrease of main current versus (dV/dt)c (typical values). Standard Types

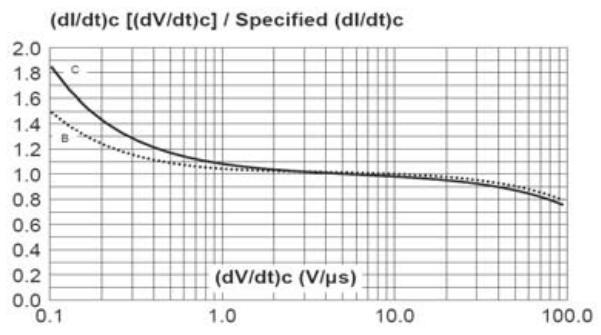


Fig. 9: Relative variation of critical rate of decrease of main current versus junction temperature.

